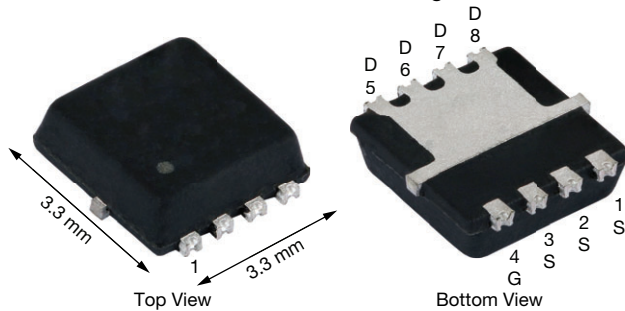


Automotive N-Channel 150 V (D-S) 175 °C MOSFET

PowerPAK® 1212-8W Single


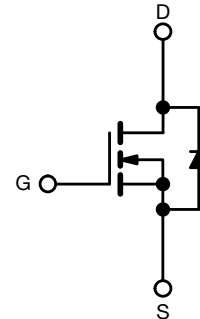
Marking code: Q052

PRODUCT SUMMARY	
V_{DS} (V)	150
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.0685
I_D (A)	18
Configuration	Single

FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE


RoHS
 COMPLIANT
 HALOGEN
FREE


N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK 1212-8W
Lead (Pb)-free and halogen-free	SQSA70CENW (for detailed order number please see www.vishay.com/doc?79776)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	150	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current ^a	$T_C = 25$ °C ^a	I_D	18	A
	$T_C = 125$ °C		11.2	
Continuous source current (diode conduction) ^a		I_S	18	
Pulsed drain current ^b		I_{DM}	40	
Single pulse avalanche current	L = 0.1 mH	I_{AS}	18	mJ
Single pulse avalanche energy		E_{AS}	16.2	
Maximum power dissipation	$T_C = 25$ °C	P_D	62.5	W
	$T_C = 125$ °C		20	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^{d, e}			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^c	R_{thJA}	81	°C/W
Junction-to-case (drain)		R_{thJC}	2.4	

Notes

- Package limited
- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8W is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		150	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.5	3.0	3.5	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 150 V	-	-	1	μA
		V _{GS} = 0 V	V _{DS} = 150 V, T _J = 125 °C	-	-	50	
		V _{GS} = 0 V	V _{DS} = 150 V, T _J = 175 °C	-	-	150	
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	10	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 7 A	-	0.0554	0.0685	Ω
		V _{GS} = 10 V	I _D = 7 A, T _J = 125 °C	-	-	0.1296	
		V _{GS} = 10 V	I _D = 7 A, T _J = 175 °C	-	-	0.1602	
Forward transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 7 A		-	11	-	S
Dynamic ^b							
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 25 V, f = 1 MHz	-	384	540	pF
Output capacitance	C _{oss}			-	270	380	
Reverse transfer capacitance	C _{rss}			-	15	22	
Total gate charge ^c	Q _g	V _{GS} = 10 V	V _{DS} = 75 V, I _D = 2 A	-	8	12	nC
Gate-source charge ^c	Q _{gs}			-	2.1	-	
Gate-drain charge ^c	Q _{gd}			-	2.1	-	
Gate resistance	R _g	f = 1 MHz		0.80	1.61	2.41	Ω
Turn-on delay time ^c	t _{d(on)}	V _{DD} = 75 V, R _L = 37.5 Ω I _D ≅ 2 A, V _{GEN} = 10 V, R _G = 1 Ω		-	10	20	ns
Rise time ^c	t _r			-	4	10	
Turn-off delay time ^c	t _{d(off)}			-	16	30	
Fall time ^c	t _f			-	10	20	
Source-Drain Diode Ratings and Characteristic ^b							
Pulsed current ^a	I _{SM}			-	-	40	A
Forward voltage	V _{SD}	I _F = 7 A, V _{GS} = 0 V		-	0.85	1.1	V
Body diode reverse recovery time	t _{rr}	I _F = 2 A, di/dt = 100 A/μs		-	43	90	ns
Body diode reverse recovery charge	Q _{rr}			-	87	175	nC
Reverse recovery fall time	t _a			-	38	-	ns
Reverse recovery rise time	t _b			-	5	-	
Body diode peak reverse recovery current	I _{RM(REC)}					-	-3.9

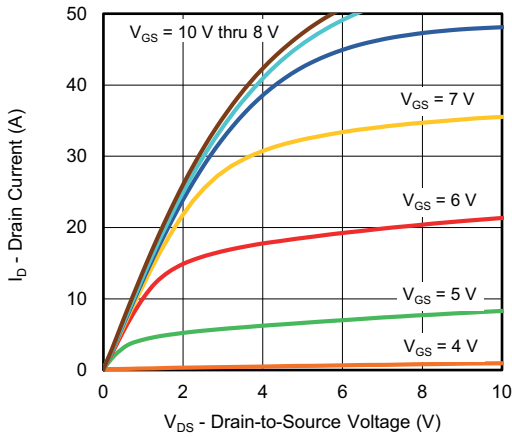
Notes

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

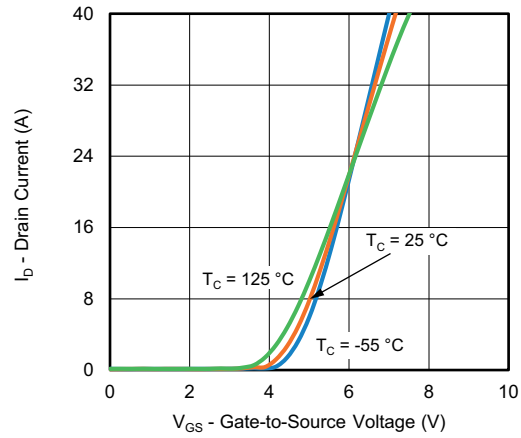
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



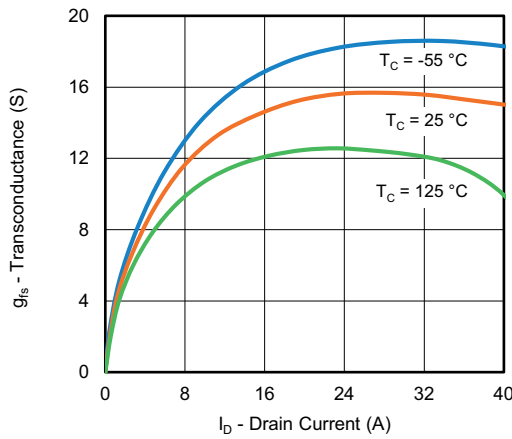
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



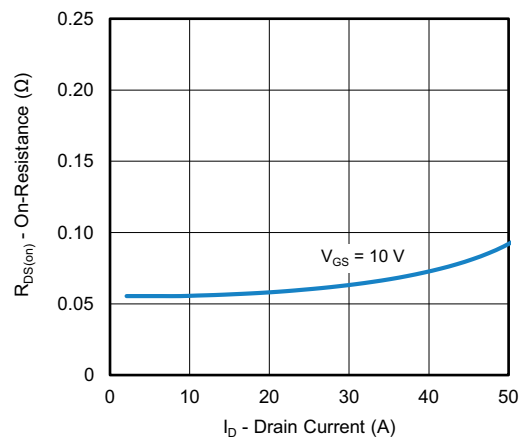
Output Characteristics



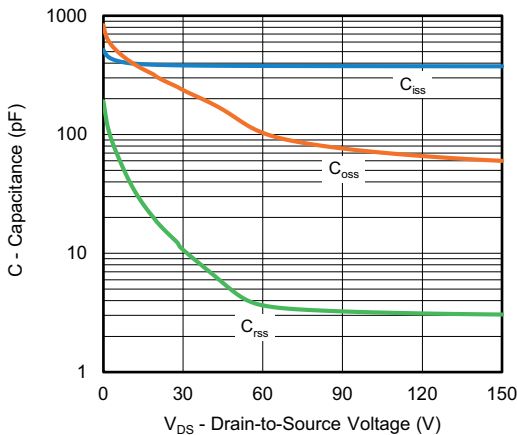
Transfer Characteristics



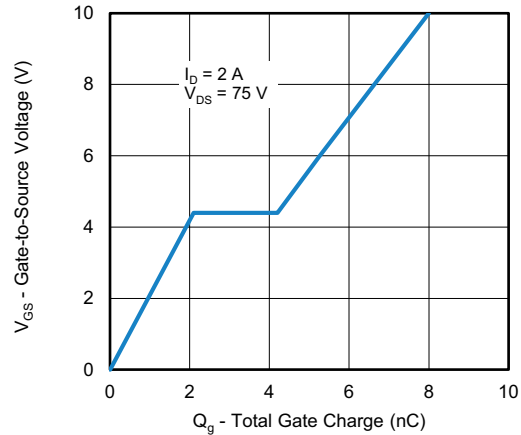
Transconductance



On-Resistance vs. Drain Current



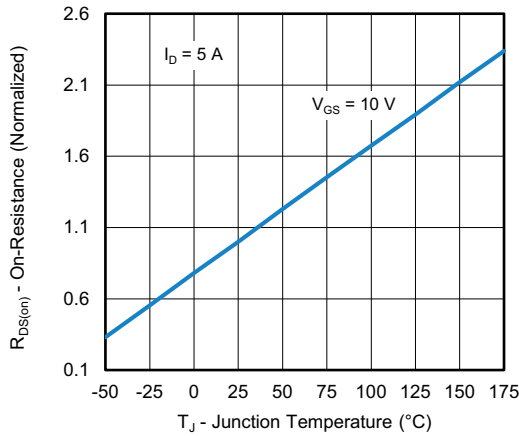
Capacitance



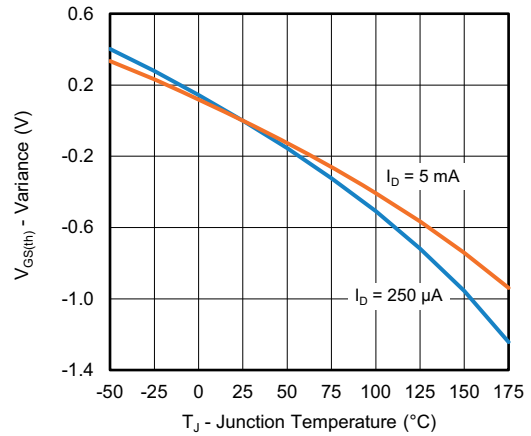
Gate Charge



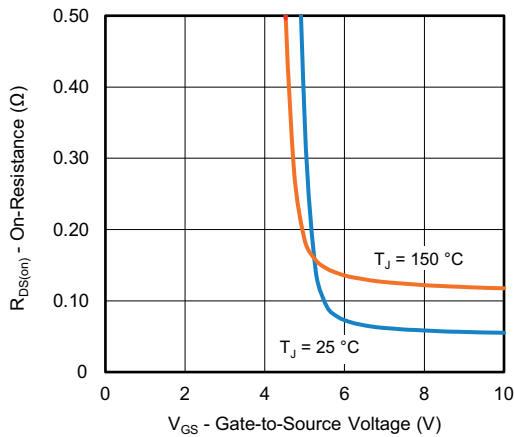
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



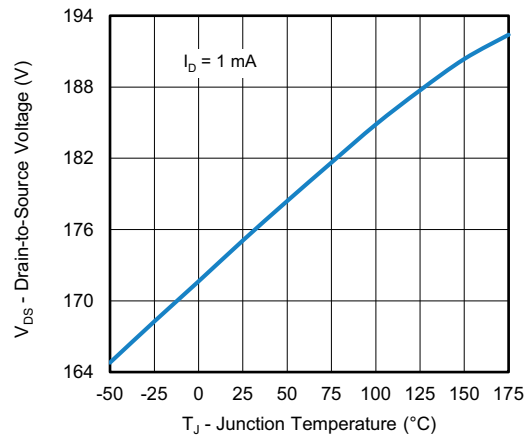
On-Resistance vs. Junction Temperature



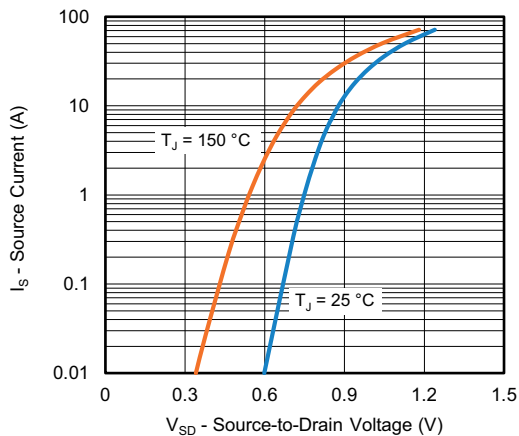
Threshold Voltage



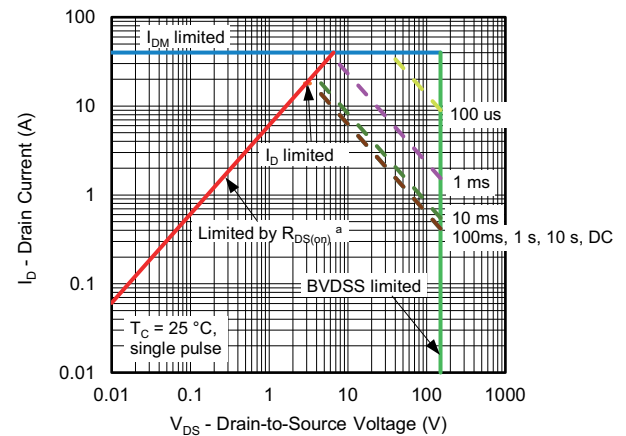
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



Source Drain Diode Forward Voltage



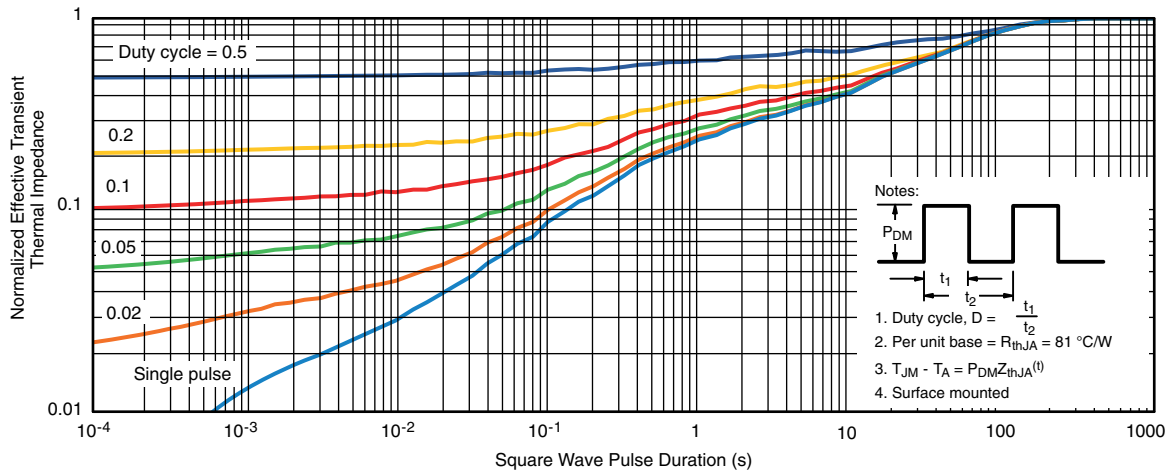
Safe Operating Area

Note

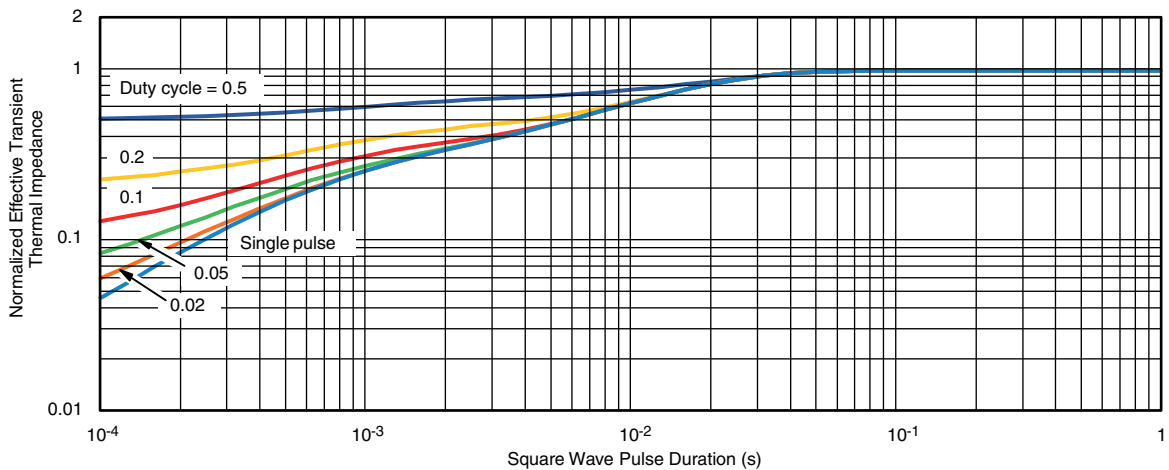
- a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified



THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^\circ\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^\circ\text{C}$)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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